Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

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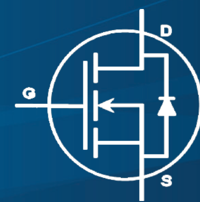
EPC2039 – Enhancement Mode Power Transistor

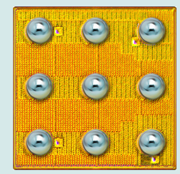
V_{DSS} , 80 V
$R_{DS(on)}$, 25 mΩ
I_D , 6.8 A



EFFICIENT POWER CONVERSION

RoHS Halogen-Free

Gallium Nitride is grown on Silicon Wafers and processed using standard CMOS equipment leveraging the infrastructure that has been developed over the last 60 years. GaN's exceptionally high electron mobility and low temperature coefficient allows very low $R_{DS(on)}$, while its lateral device structure and majority carrier diode provide exceptionally low Q_G and zero Q_{RR}. The end result is a device that can handle tasks where very high switching frequency, and low on-time are beneficial as well as those where on-state losses dominate.



EPC2039 eGaN® FETs are supplied only in passivated die form with solder bumps
Die Size: 1.35 mm x 1.35 mm

Applications
- High Speed DC-DC conversion
- Wireless Power Transfer
- LiDAR/Pulsed Power Applications

Benefits
- Ultra High Efficiency
- Ultra Low $R_{DS(on)}$
- Ultra low Q_G
- Ultra small footprint

www.epc-co.com/epc/Products/eGaNFETs/EPC2039.aspx

Maximum Ratings			
V_{DS}	Drain-to-Source Voltage (Continuous)	80	V
	Drain-to-Source Voltage (up to 10,000 5ms pulses at 150˚C)	96	
I_D	Continuous (T_A = 25˚C, $R_{θJA}$= 70˚C/W)	6.8	A
	Pulsed (25˚C, T_{PULSE} = 300 µs)	50	
V_{GS}	Gate-to-Source Voltage	6	V
	Gate-to-Source Voltage	-4	
T_J	Operating Temperature	-40 to 150	˚C
T_{STG}	Storage Temperature	-40 to 150	

Static Characteristics (T_J= 25˚C unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-to-Source Voltage	V_{GS} = 0 V, I_D = 300 µA	80			V
I_{DSS}	Drain Source Leakage	V_{DS} = 64 V, V_{GS} = 0 V		20	250	µA
I_{GSS}	Gate-to-Source Forward Leakage	V_{GS} = 5 V		0.2	2	mA
	Gate-to-Source Reverse Leakage	V_{GS} = -4 V		20	250	µA
$V_{GS(TH)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 2 mA	0.8	1.6	2.5	V
$R_{DS(on)}$	Drain-Source On Resistance	V_{GS} = 5 V, I_D = 6 A		20	25	mΩ
V_{SD}	Source-Drain Forward Voltage	I_S = 0.5 A, V_{GS} = 0 V		2.5		V

All measurements were done with substrate shorted to source.

Thermal Characteristics			
		TYP	UNIT
$R_{θJC}$	Thermal Resistance, Junction to Case	3	˚C/W
$R_{θJB}$	Thermal Resistance, Junction to Board	28	˚C/W
$R_{θJA}$	Thermal Resistance, Junction to Ambient (Note 1)	81	˚C/W

Note 1: $R_{θJA}$ is determined with the device mounted on one square inch of copper pad, single layer 2 oz copper on FR4 board.
See http://epc-co.com/epc/documents/product-training/Appnote_Thermal_Performance_of_eGaN_FETs.pdf for details.

Dynamic Characteristics (T_J = 25˚C unless otherwise stated)						
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
C_{ISS}	Input Capacitance			210	260	
C_{RSS}	Reverse Transfer Capacitance	V_{DS} = 40 V, V_{GS} = 0 V		2		pF
C_{OSS}	Output Capacitance			115	175	
$C_{OSS(ER)}$	Effective Output Capacitance, Energy Related (Note 2)	V_{DS} = 0 to 100 V, V_{GS} = 0 V		155		
$C_{OSS(TR)}$	Effective Output Capacitance, Time Related (Note 3)			190		
R_G	Gate Resistance			0.5		Ω
Q_G	Total Gate Charge	V_{DS} = 40 V, V_{GS} = 5 V, I_D = 6 A		1910	2370	
Q_{GS}	Gate-to-Source Charge			760		
Q_{GD}	Gate-to-Drain Charge	V_{DS} = 40 V, I_D = 6 A		420		
$Q_{G(TH)}$	Gate Charge at Threshold			560		pC
Q_{OSS}	Output Charge	V_{DS} = 40 V, V_{GS} = 0 V		7640	11500	
Q_{RR}	Source-Drain Recovery Charge			0		

Note 2: $C_{OSS(ER)}$ is a fixed capacitance that gives the same stored energy as C_{OSS} while V_{DS} is rising from 0 to 50% BV_{DSS}.
Note 3: $C_{OSS(TR)}$ is a fixed capacitance that gives the same charging time as C_{OSS} while V_{DS} is rising from 0 to 50% BV_{DSS}.

Figure 1: Typical Output Characteristics at 25°C

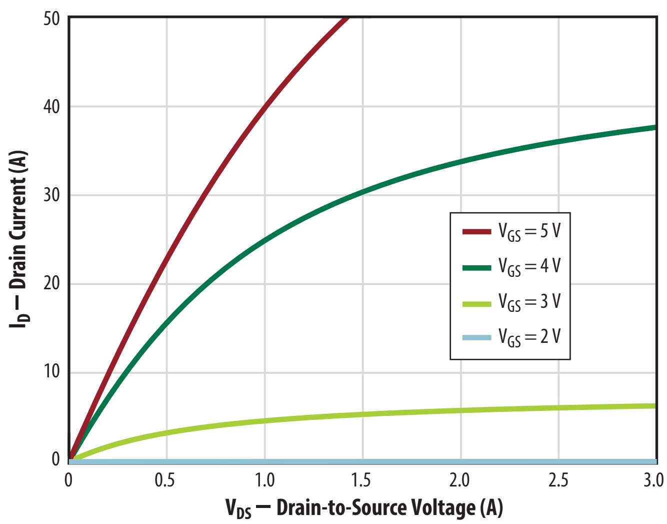


Figure 2: Transfer Characteristics

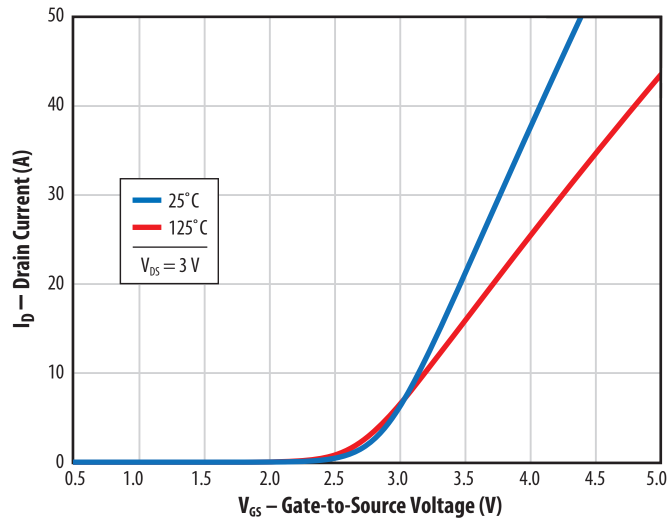


Figure 3: $R_{DS(on)}$ vs. V_{GS} for Various Drain Currents

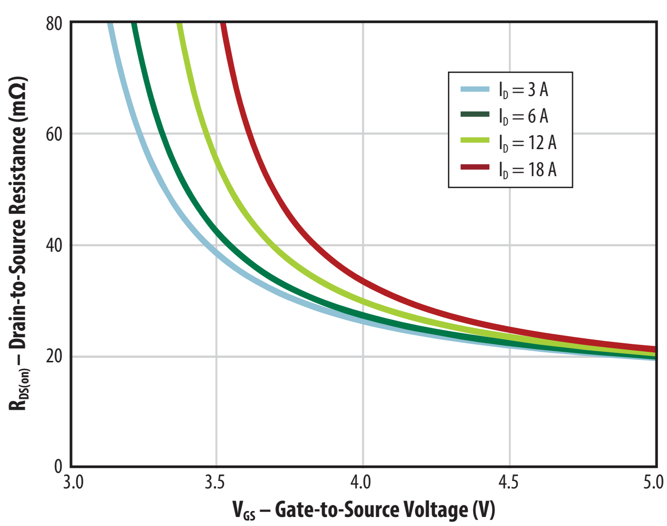


Figure 4: $R_{DS(on)}$ vs. V_{GS} for Various Temperatures

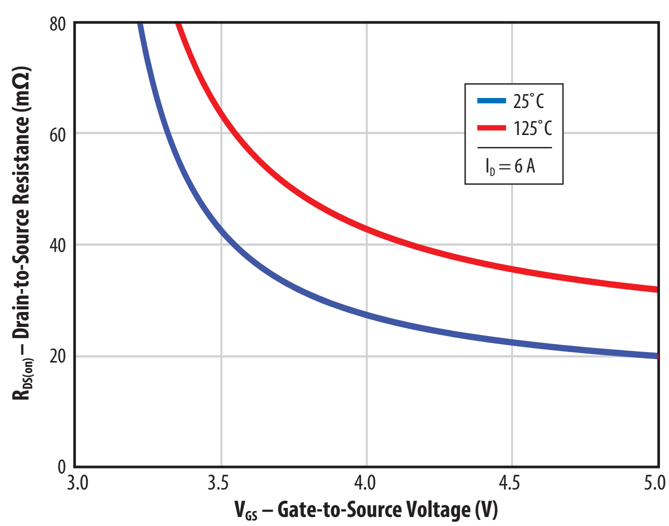


Figure 5a: Capacitance (Linear Scale)

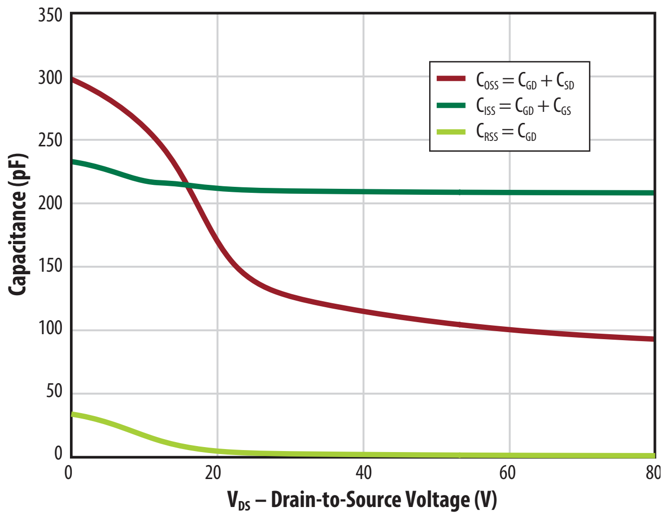


Figure 5b: Capacitance (Log Scale)

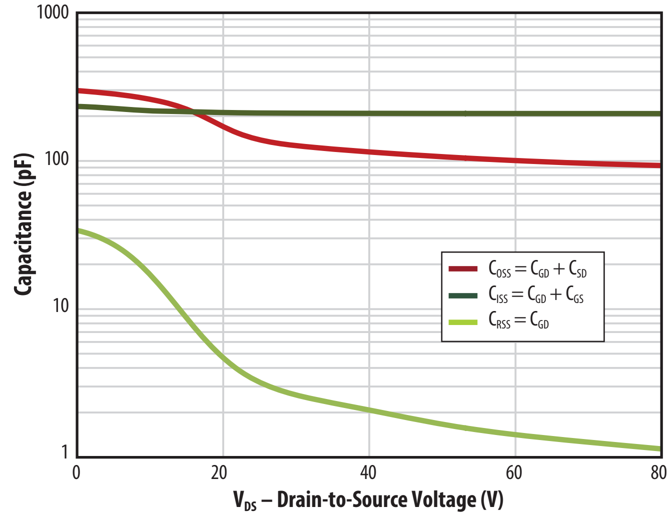


Figure 6: Gate Charge

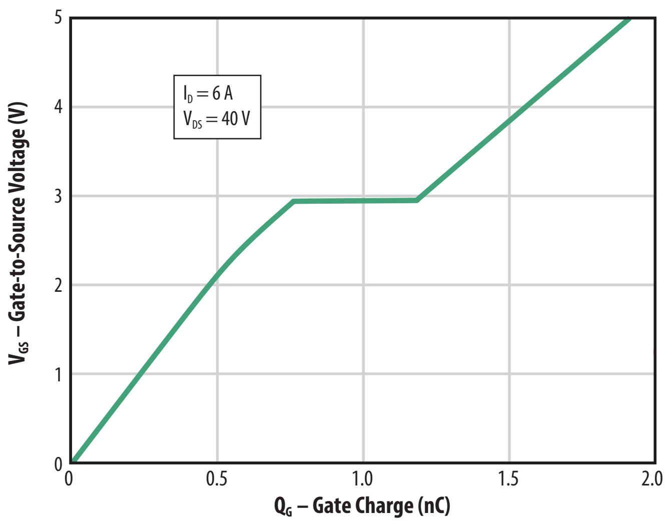


Figure 7: Reverse Drain-Source Characteristics

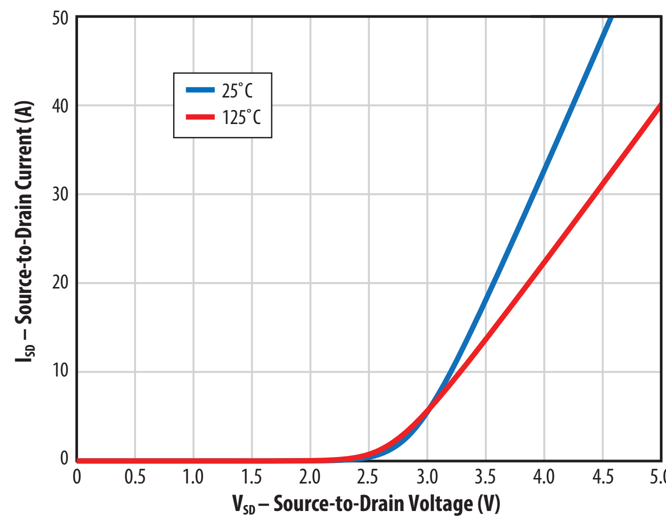


Figure 8: Normalized On Resistance vs. Temperature

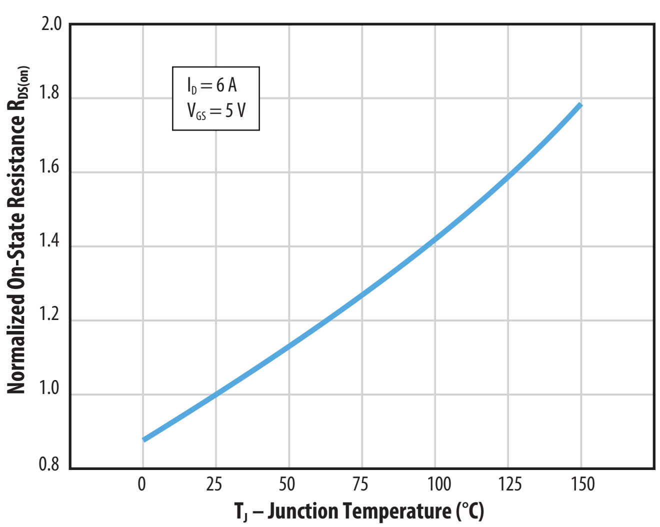
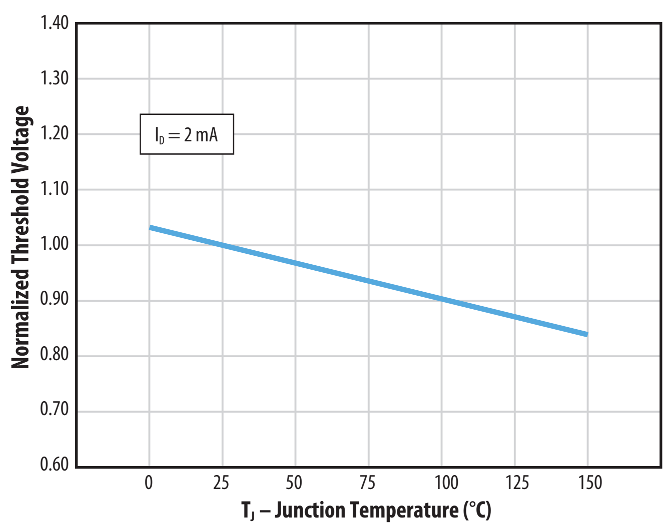
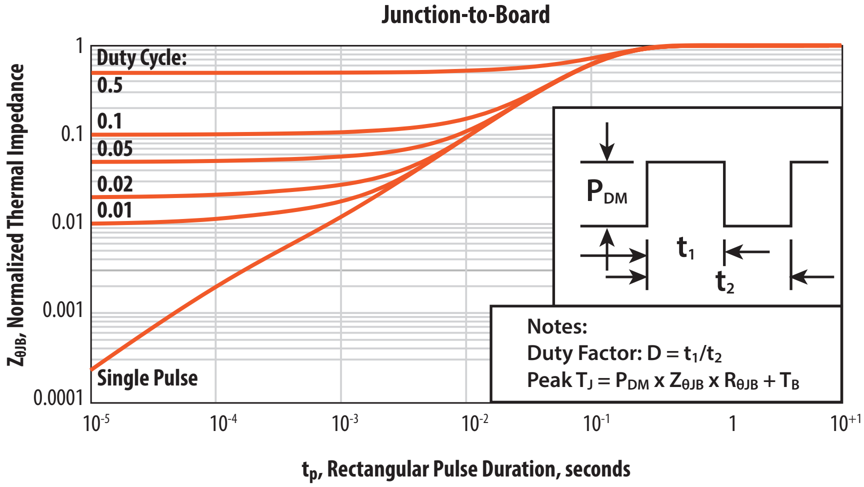


Figure 9: Normalized Threshold Voltage vs. Temperature



All measurements were done with substrate shortened to source.

Figure 10: Transient Thermal Response Curves



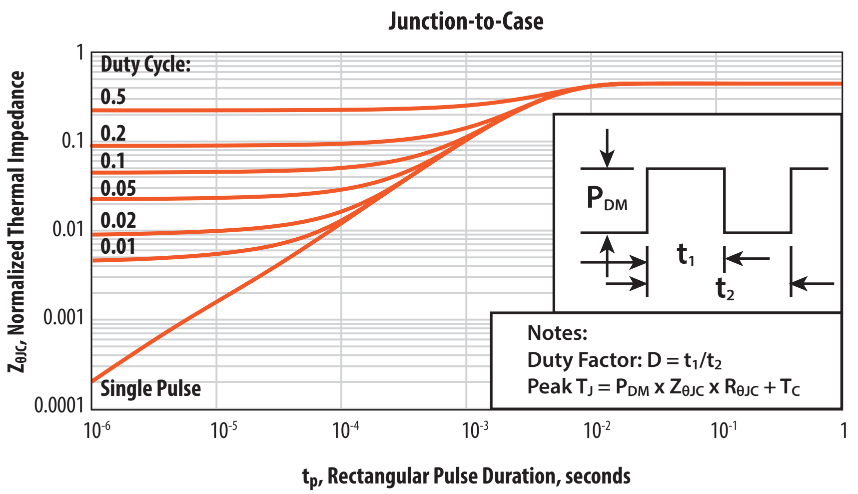
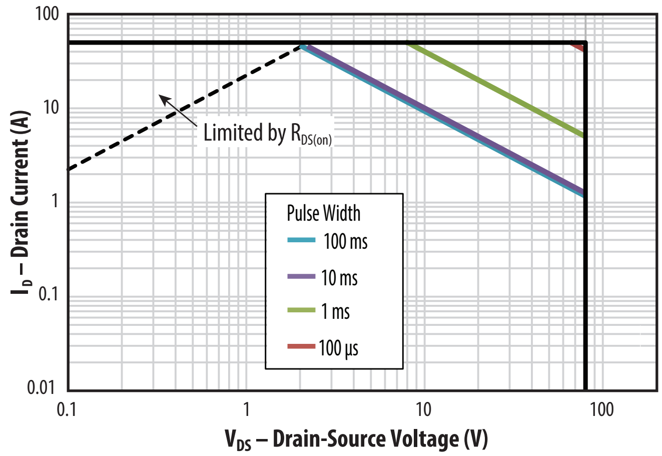


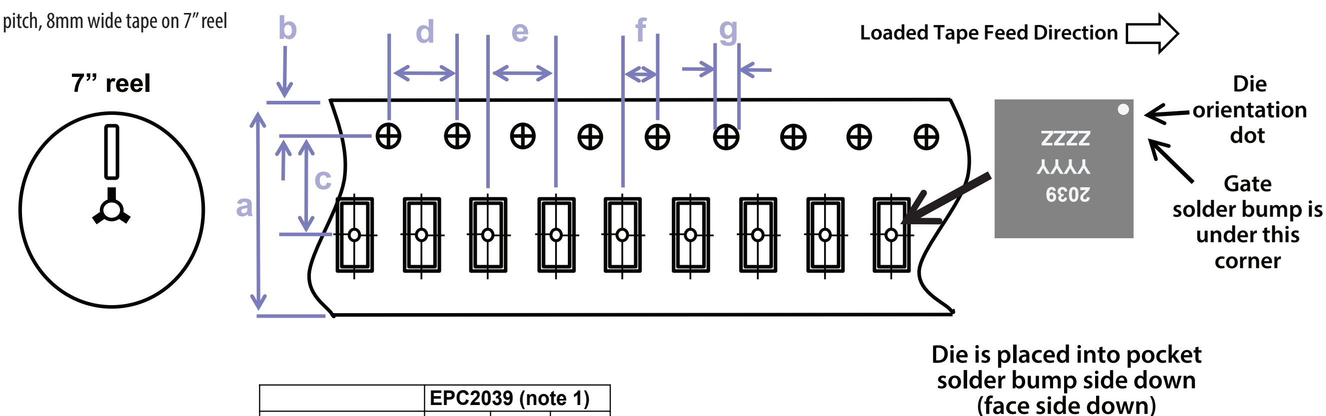
Figure 11: Safe Operating Area



T_J = Max Rated, T_C = +25°C, Single Pulse

TAPE AND REEL CONFIGURATION

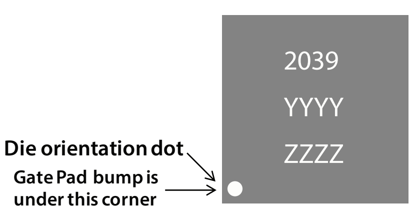
4mm pitch, 8mm wide tape on 7" reel



	EPC2039 (note 1)		
Dimension (mm)	target	min	max
a	8.00	7.90	8.30
b	1.75	1.65	1.85
c (see note)	3.50	3.45	3.55
d	4.00	3.90	4.10
e	4.00	3.90	4.10
f (see note)	2.00	1.95	2.05
g	1.5	1.5	1.6

Note 1: MSL 1 (moisture sensitivity level 1) classified according to IPC/JEDEC industry standard.
Note 2: Pocket position is relative to the sprocket hole measured as true position of the pocket, not the pocket hole.

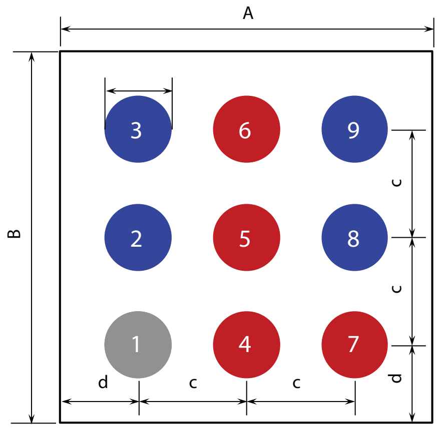
DIE MARKINGS



Part Number	Laser Markings		
	Part # Marking Line 1	Lot_Date Code Marking Line 2	Lot_Date Code Marking Line 3
EPC2039	AA	YYYY	ZZZZ

DIE OUTLINE

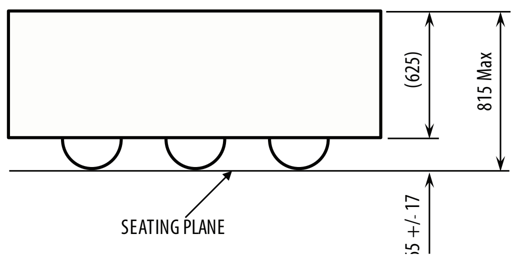
Solder Bump View



Pad 1 is Gate;
Pads 4, 5, 6, 7 are Drain;
Pads 2, 3, 8, 9 are Source

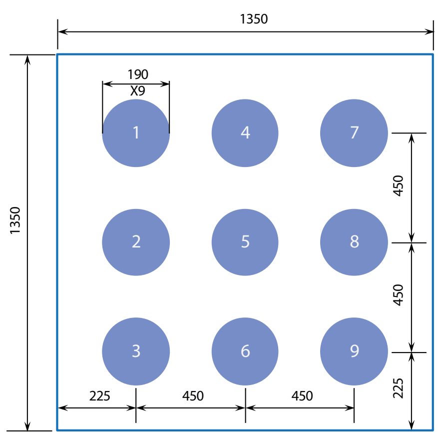
DIM	MIN	Nominal	MAX
A	1320	1350	1380
B	1320	1350	1380
c	450	450	450
d	210	225	240
e	187	208	229

Side View



RECOMMENDED LAND PATTERN

(measurements in µm)



The land pattern is solder mask defined

Solder mask is 10µm smaller per side than bump

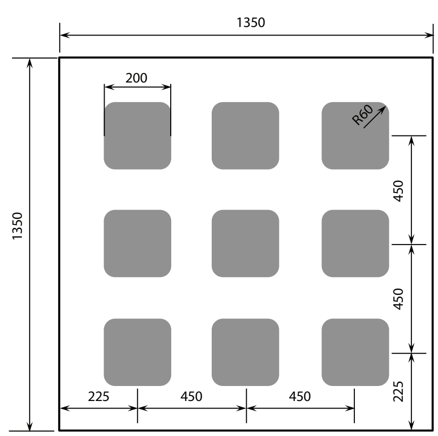
Pad 1 is Gate;

Pads 4, 5, 6, 7 are Drain;

Pads 2, 3, 8, 9 are Source

RECOMMENDED STENCIL DRAWING

(measurements in µm)



Recommended stencil should be 4mil (100µm) thick, must be laser cut, openings per drawing.

Intended for use with SAC305 Type 4 solder, reference 88.5% metals content.

Additional assembly resources available at http://epc-co.com/epc/DesignSupport/AssemblyBasics.aspx